

VIASYSTEMS ZHONGSHAN

PCB



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PROCESS CAPABILITY

- » Line / Space - Print / Etch Inner Layer3/3 mil
- External Layer.....4/4 mil
- » Impedance Control±10%
- » Solder Mask Dam3 mil
- » Board Thickness Tolerance±10%
- » Warp (mils/inch)5 mil/inch
- » Internal Annular Ring - ≤ 12 layers(mil)DHS+12
- » External Annular Ring (mil)DHS+12
- » Hole to Edge Tolerance.....±5 mil
- » Feature to Edge Tolerance.....±5 mil

CORE COMPETENCY

- » High-volume Double-sided Through 10 Layer Printed Circuit Boards

KEY DATA

- » 799,000 square feet
- » Maximum Panel Size: 18" x 24"
- » Maximum Board Thickness: 160 mil
- » Aspect Ratio: 10 : 1
- » Layer Count: 1 - 10
- » Tracks & Gaps: 4/4 (External) & 3/3 (Internal)
- » Minimum Core Thickness: 3 mil
- » Tab Plating
- » Heat-sink
- » Controlled impedance
- » Silver through hole
- » Heavy Copper

CERTIFICATIONS

- » ISO 9001:2000
- » ISO 14001:2004
- » TL 9000
- » ISO /TS 16949:2002
- » UL 796
- » Bellcore Compliant

PHYSICAL ATTRIBUTES

- » Maximum Layer Count 10
- » Inner Copper Weight0.5 – 12 oz
- » Outer Copper Weight.....0.5 – 5 oz
- » SMT Pitch 12 mil
- » Core Thickness3 – 96 mil
- » Board Thickness 18 – 160 mil
- » Plating Aspect RatioMax 10:1

MATERIALS

- » FR4 (Tg 140°C, 150°C and 170°C), Lead Free and Halogen-Free Material CEM1, CEM3, FR1

SURFACE FINISHES

- » HASL
- » OSP
- » Immersion Silver
- » Immersion Tin
- » Hard Gold Tab
- » Immersion Gold
- » Carbon Ink
- » Lead Free HAL (SN 100CL)

SOLDER MASK

- » Taiyo, Tamura, Nanya, Probimer, Enthone

TEST EQUIPMENT

- » AOI - Orbotech AOI Machine
- » E-Test - Kaima / OS / Mason E-Tester
- » Lab. Testing - Cross-section
- SIR
- Ionic Chromatography
- Thermal Cycling

CAD/CAM

- » Orbotech/Valor Workstation
- » Orbotech Laser Plotter

CAPACITY

- » Inner Capacity: 233,000 square feet per week
- » Outer Capacity: 257,000 square feet per week

MANUFACTURING EQUIPMENT

- » Board Cutting - ACS Auto Sawing Machine
- » Inner D/F - C'Sun Laminator, Hakuto Laminator & Cedal Laminator
- C'Sun and ORC Exposer Machine
- Automatech and ORC Automatic Exposure Machine
- » DES - Hollmuller DES Line + Kalex DES Line
- » Black Oxide - Gainford Black Oxide Line
- » Pressing - Dah Tyan / Burkle Mass Lamination with Seiko Bonding Machine
- Lauffer Lamination System (Capable for Pin Lamination)
- » Drilling - Hitachi / Excellon Drilling Machine
- » Outer D/F - Cedal Laminator, Hakuto Laminator and Dynachem Laminator
- Co-light & ORC Exposer Machine
- ORC Automatic Exposure Machine
- » SES - U-Tah and UCE SES Line
- » Solder Mask - Group Up Electrostatic Spray Coating Machine
- ORC Auto Exposure Machine
- » HASL - HALCO HASL Machine
- Quicksilver Vertical HASL (LF
- Serion HC-7 Hole Checking Machine
- » Profiling -Hitachi / Sogotec / Excellon Routing Machine
- Lenz, NCV-600 and VMS-4000 V-cut Machine